

Abstract of the Disclosure

**SUBSTRATE POLISHING METHOD AND DEVICE
THEREOF**

A circular substrate is held and rotated by a holding/rotating mechanism, a polishing tape is transferred intermittently or continuously by a tape transfer mechanism, a detour polishing part in a tape polishing mechanism is pressure-contacted to an inner peripheral end surface of a round hole by a pressure-contacting mechanism, the detour polishing part is rocked intermittently or continuously in a direction opposite to the inner peripheral end surface by a polishing part rocking mechanism to polish the surface into a chamfered surface or a round surface, where a substrate polishing device includes a tape transfer mechanism C, a tape polishing mechanism D with a detour polishing part K consisting of a sideward detouring portion T₃ of the polishing tape T guided to detour sideward by a detour guide part C₃ for polishing an inner peripheral end surface M of a round hole Q, and a polishing part rocking mechanism F.

FIG. 1



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